505179121 11/07/2018

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5225889

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DONGSU KIM	06/25/2018

RECEIVING PARTY DATA

Name:	KOREA ELECTRONICS TECHNOLOGY INSTITUTE	
Street Address:	25, SAENARI-RO, BUNDANG-GU	
Internal Address:	s: SEONGNARI-SI	
City:	GYEONGGI-DO	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	stal Code: 463-816	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16064611

CORRESPONDENCE DATA

Fax Number: (770)951-0933

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 7709339500

Email: tina.schafer@thomashorstemeyer.com

Correspondent Name: RANDY R. SCHOEN

Address Line 1: 3200 WINDY HILL ROAD

Address Line 2: SUITE 1600E

Address Line 4: ATLANTA, GEORGIA 30339

ATTORNEY DOCKET NUMBER:	222110-1220 (KETI)
NAME OF SUBMITTER: RANDY R. SCHOEN	
SIGNATURE:	/Randy R. Schoen/
DATE SIGNED:	11/07/2018
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 2

source=UF_15045__222110-1220__Declaration-Assignment__KETI_#page1.tif source=UF_15045__222110-1220__Declaration-Assignment__KETI_#page2.tif

PATENT 505179121 REEL: 047435 FRAME: 0150

DECLARATION AND ASSIGNMENT

As a below-named inventor, I/we hereby declare that I/we believe I/we am/are the original inventor(s) or an original joint inventor of a claimed invention in the patent application for United States letters patent, entitled, "HYDROTHERMALLY GROWN BaTiO₃, SrTiO₃, AND Ba_xSr_{1-x}TiO₃ ON TiO₂ NANOTUBE LAYERS FOR ULTRA-HIGH CHARGE DENSITY CAPACITORS," (the "Invention") that

was signed by me/us on	(attached) and/or
■ was filed on June 21, 2018, Serial No. 16/064,611	
(the "Application").	

The Application was made or authorized to be made by me, and I/we have reviewed and understand its contents, including the claims.

I/we hereby acknowledge the duty to disclose information that is material to patentability of the Invention in accordance with Title 37, Code of Federal Regulations, § 1.56.

I/we hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years or both.

I/we am/are assigning all my/our rights in the Invention to **Korea Electronics Technology Institute,** having a place of business at 25, Saenari-ro, Bundang-gu, Seongnari-si, Gyeonggi-do, Republic of Korea 463-816, or its assignee or designee.

THEREFORE, for valuable consideration, the sufficiency and receipt of which I/we hereby acknowledge, I/we confirm and ratify the sale, assignment, and transfer to **Korea Electronics Technology Institute**, its successors and assigns, all my/our rights in the Invention, the Application, and all other patent applications and patents for the Invention which may be applied for or granted, including, all divisional, continuing, substitute, renewal, reissue, reexamination, counterpart, substitute, extension, and all other applications for letters patent which are or have been filed for the Invention in the United States, its territorial possessions, and all foreign countries and in all patents and extensions which may be granted for the Application.

I/We hereby authorize and request patent office officials in the United States and in all foreign countries to issue any patents that are granted for the Application to **Korea Electronics Technology Institute** as the assignee of my/our entire right, title, and interest in the patents.

I/We hereby assign to **Korea Electronics Technology Institute**, its successors and assigns, all of my/our rights to sue for and recover damages and profits with respect to past infringements or unauthorized uses of any patent that issues on the Application or unpaid royalties with respect to use of any rights in the Application that occurred before the execution of this Assignment.

Page 1 of 2

PATENT REEL: 047435 FRAME: 0151 I/We agree that, in regard to the Application, I/we will communicate to Korea Electronics Technology Institute or its representatives any facts that are known to me/us; testify in any legal proceedings; sign all lawful papers; execute all divisional, continuing, substitute, renewal, reissue, and other applications for letters patent; execute all necessary papers; make all rightful oaths; and generally do everything possible to aid Korea Electronics Technology Institute, its successors and assigns, to obtain and enforce all rights with respect to the Application in the United States, its territorial possessions, and all foreign countries.

Signed:		
Name:	Dongsp-Kim	
Address:	25, Saenari-ro, Bundang-gu	
	Seonganam-si	
	Gyeonggi-do, 463-816	
	KR	
Date:	1/23/2012	
		Witness Signature: <u> </u>
		* v.*
		WANTED THE STATE OF THE STATE O
Date:	06/24/2018	Witness Printed: <u>Jun-Chul Kim</u>
		Witness Signature:
	6/25/2018	Witness Printed: <u>Jong-Min Yook</u>
Date:	0/ 000/ 000/0	

Page 2 of 2